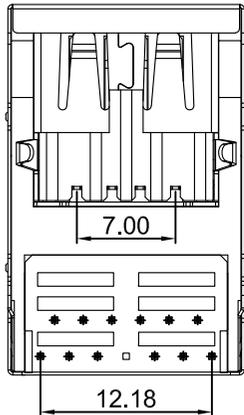
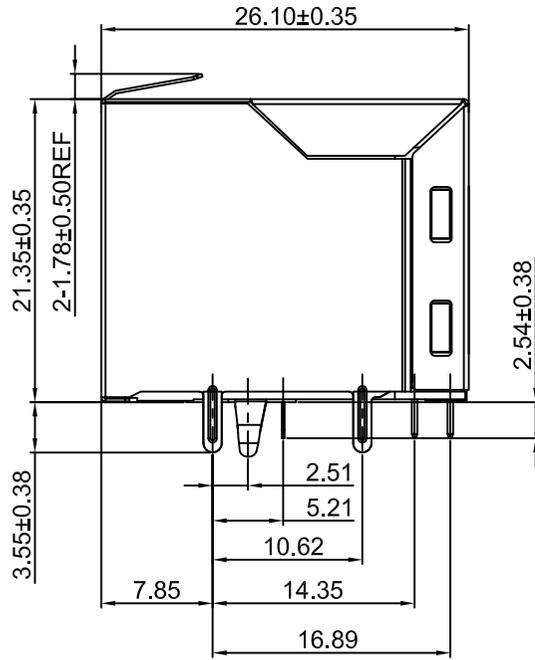
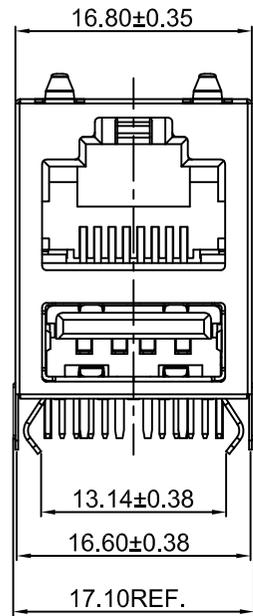


GP Component

1. MECHANICAL:



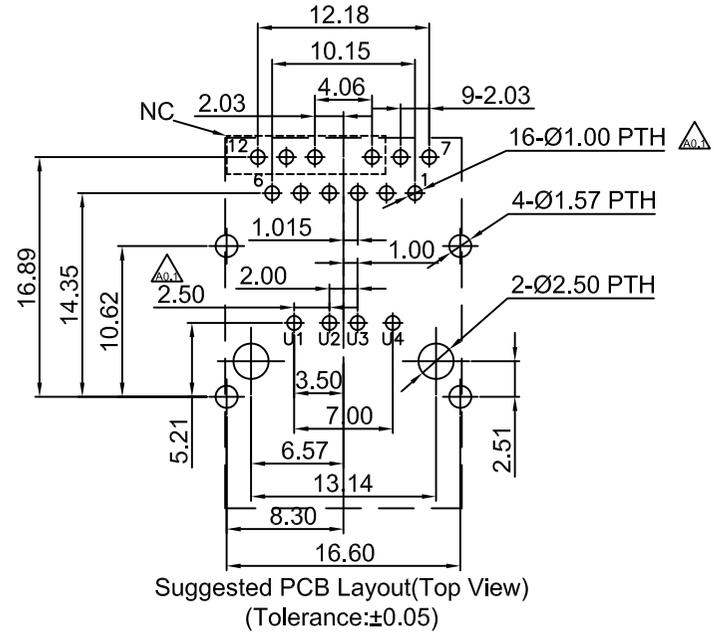
1. Material:

- 1.1 Housing: PBT UL94V-0 Black.
- 1.2 Insert core and Cover: PBT UL94V-0 Black.
- 1.3 Contact : Phosphor Bronze, Gold plated on contact area 6u", Tin plated on solder area 80u" min, overall nickel plating 30u" min.
- 1.4 Input Terminal : Brass, Tin plated on solder area 80u" min, Ni underplated overall 30u" min.
- 1.5 RJ45 shielding: Copper alloy with Nickel plated.
- 1.6 USB Housing: PBT UL94V-0 Black.
- 1.7 USB Terminal : Brass, Gold plated on contact area Fu", Tin plated on solder area 80u" min, Ni underplated overall 30u" min.
- 1.8 USB Shielding: Iron alloy with Nickel plated.

2. Environmental requirements:

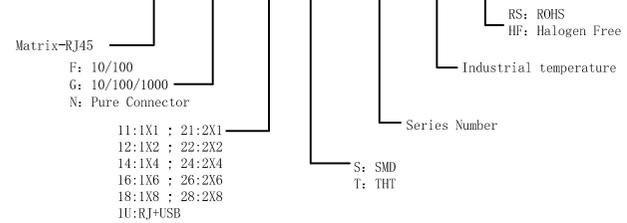
- 2.1 Lead-free process, compliant RoHS.

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0.1			Modify Pcb Size Annotation	2025/05/06	Vince
A0.2			Modify Panel cutout	2025/05/09	Vince
A0.3			Modify Panel cutout tolerance	2025/05/12	Vince



MATRIX PART NO:

MRJ N-1U T 2009 T RS



USB 2.0 CONTACT PINS	
Pin NUMBER	SIGNAL NAME
U1	VBUS
U2	D-
U3	D+
U4	GND
Shell	Shield

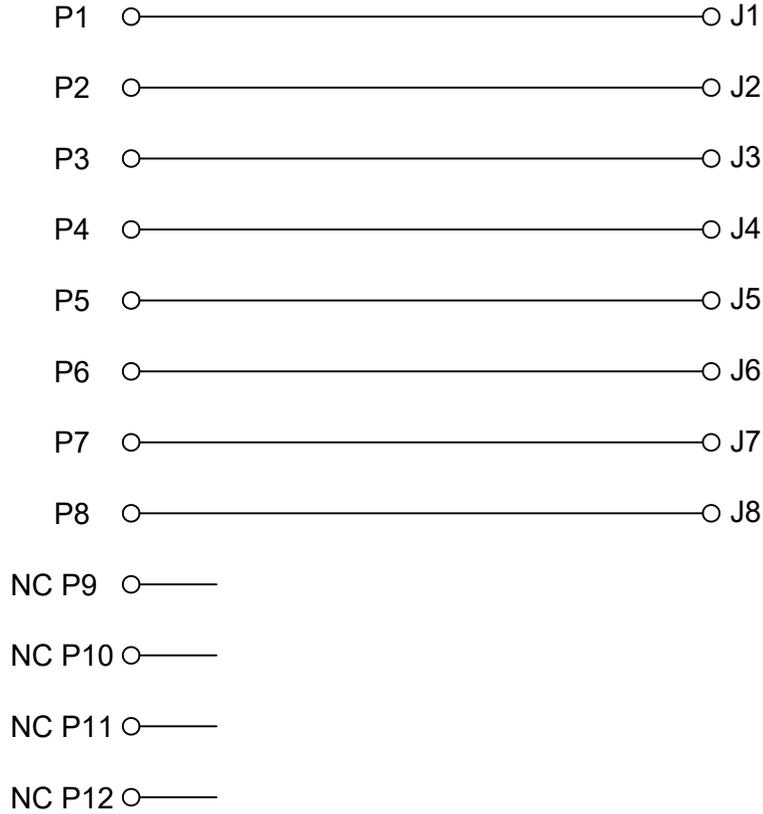


Matrix Electronics Co., Ltd

TOLERANCE: X X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 X° ±2°	DESIGN BY : Vince Chen	DATE : 2025/05/12	PART NAME: RJ45+USB2.0 CONN, W/O LED	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY: Hanson Huang	DATE : 2025/05/12	PART NO.	MRJN-1UT2009TRS
	APPROVED BY1: Richard Hsieh	DATE : 2025/05/12	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2025/05/12	DRAW NO.	
			SHEET NO.	1 OF 3

GP Component

2.SCHEMATIC:



3.Electrical Specification @25°C:

- 3.1 Voltage rating:125V AC.
- 3.2 Current rating:1.5AMP.
- 3.3 Insulation resistance: 500 MΩ minimum initial after 500V DC for 1minute.
- 3.4 Low level Contact resistance:
Single terminal 20 mΩ Max initial
40 mΩ maximum after durability test.
- 3.5 Hi-Pot Test: Between adjacent pins 1000VDC/1mA/60sec.
- 4.Operating and Storage Temperature:
 - 4.1 Operating Temperature : -40°C to +85°C.
 - 4.2 Storage Temperature : -40°C to +85°C.
- 5.Wave soldering peak temperature:260°C.
- 6.RJ45 JACK complies with IEC60603-7 standard.

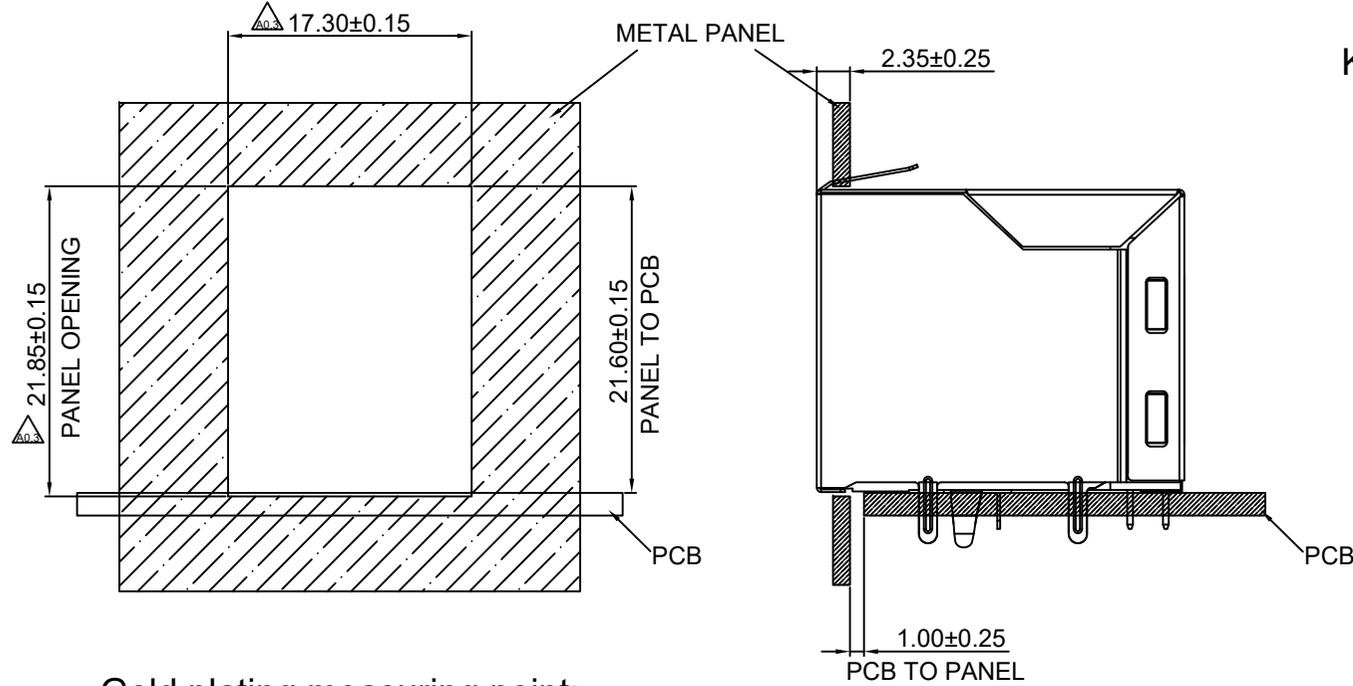
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 Matrix Electronics Co.,Ltd					
TOLERANCE: X X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 X° ±2°		DESIGN BY : Vince Chen	DATE : 2025/05/12	PART NAME: RJ45+USB2.0 CONN, W/O LED	
 UNIT: mm [inch]		CHECKED BY: Hanson Huang	DATE : 2025/05/12	PART NO. MRJN-1UT2009TRS	PART NO. MRJN-1UT2009TRS
		APPROVED BY1: Richard Hsieh	DATE : 2025/05/12	MOLD NO. NA	MOLD NO. NA
SCALE:1:1 SIZE:A4		APPROVED BY2: Richard Hsieh	DATE : 2025/05/12	DRAW NO. SHEET NO. 2 OF 3	DRAW NO. SHEET NO. 2 OF 3

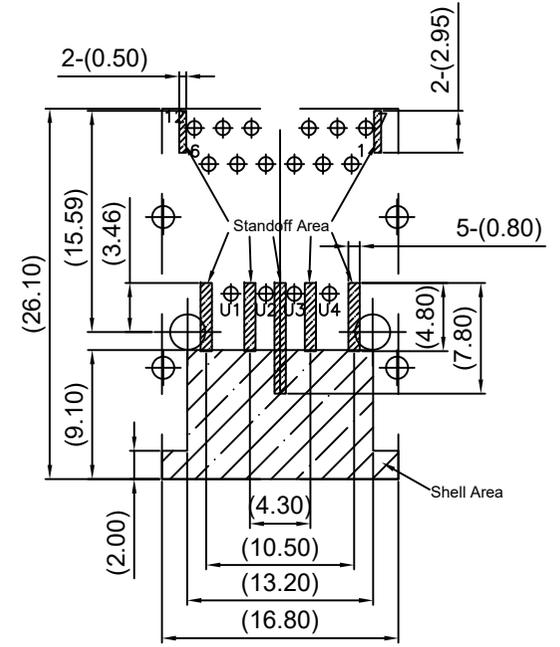
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0.1			Modify Pcb Size Annotation	2025/05/06	Vince
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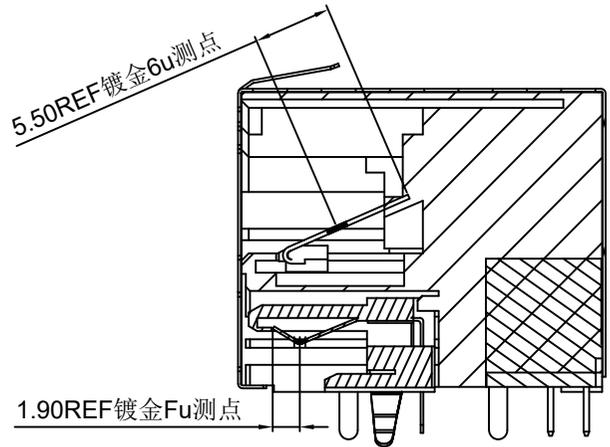
Recommended Panel cutout:



KEEP-OUT AREA (Top View):



Gold plating measuring point:





Matrix Electronics Co., Ltd

TOLERANCE: X X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 X° ±2°		DESIGN BY : Vince Chen	DATE : 2025/05/12	PART NAME: RJ45+USB2.0 CONN, W/O LED	
		CHECKED BY: Hanson Huang	DATE : 2025/05/12	PART NO.	MRJN-1UT2009TRS
		APPROVED BY1: Richard Hsieh	DATE : 2025/05/12	MOLD NO.	NA
		APPROVED BY2: Richard Hsieh	DATE : 2025/05/12	DRAW NO.	
SCALE:1:1	SIZE:A4			SHEET NO.	3 OF 3